

OL-NX5P1100

WLCSP12: wafer level chip-scale package; 12 bumps; 1.36 x 1.66 x 0.51 mm, 0.4 mm pitch (Backside coating included)

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	20-12-2013

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.63	-	1.66	1.69	mm
E	package width	1.33	-	1.36	1.39	mm
A	seated height	0.47	-	0.51	0.55	mm
A ₂	package height	0.29	-	0.31	0.34	mm
e	nominal pitch	-	-	0.4	-	m
n ₂	actual quantity of termination	-	-	12	-	



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2. Package outline

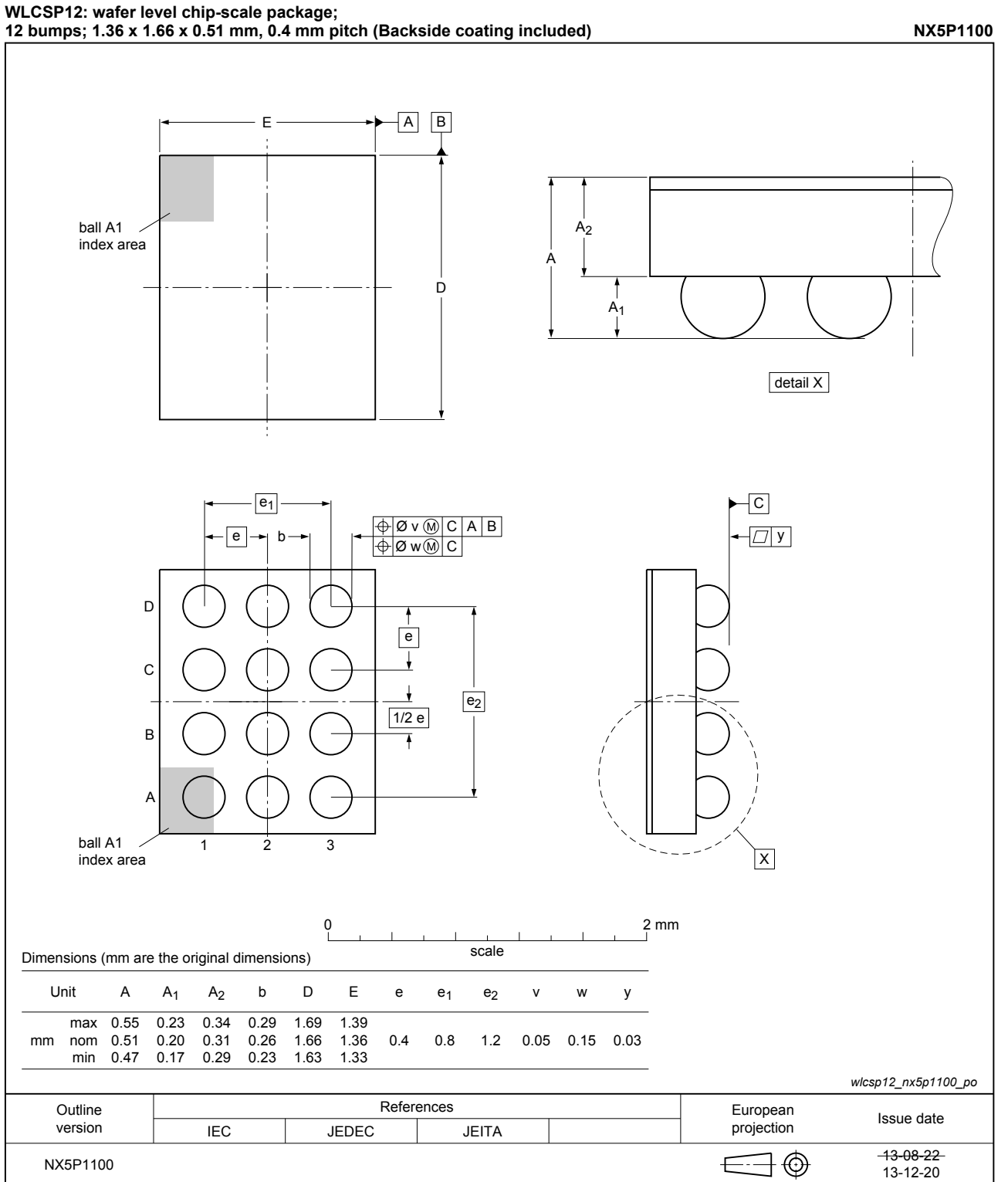


Fig. 1. Package outline WLCSP (OL-NX5P1100)

WLCSP12: wafer level chip-scale package; 12
bumps; 1.36 x 1.66 x 0.51 mm, 0.4 mm pitch
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3. Legal information

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